

[Title of Invention] PALLADIUM (PD)-COATED COPPER WIRE FOR BALL BONDING

[Title of Document] Abstract

[Problems to be Solved]

The present invention is made to solve a problem in which an intermetallic compound of Cu and Al is formed, by the FAB of a mass-produced bonding wire, at an early stage in the interface of bonding between a molten ball and an aluminum pad, and has an object to provide a palladium (Pd)-coated copper wire for ball bonding with which it is possible to uniformly disperse palladium (Pd) fine particles on the surface of the molten ball and which is suitable for mass production.

[Constitution of Invention]

In the palladium (Pd)-coated copper wire for ball bonding according to the present invention, the palladium (Pd)-coated copper wire for ball bonding has a diameter of 10 to 25 μm , a palladium (Pd) drawn layer is formed on a core formed of a copper alloy in which the purity of pure copper (Cu) or copper (Cu) is 98% by mass or more and the palladium (Pd) drawn layer is a palladium (Pd) layer which contains sulfur (S), phosphorus (P), boron (B) or carbon (C).

[Figure] Fig. 1